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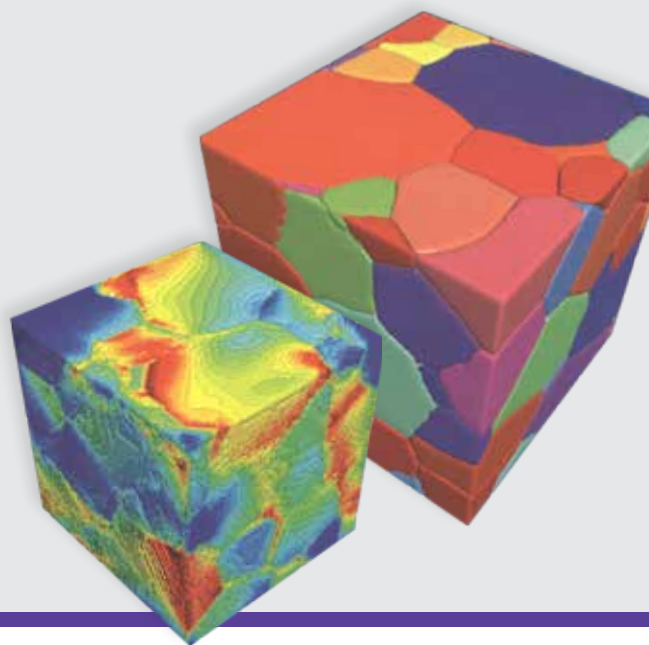
The 4th International Congress on

3DMS

3D Materials Science 2018

June 10–13, 2018

**Kulturværftet (Culture Yard) Conference Center
Helsingør (Elsinore), Denmark**



Fast forward your materials research impact by presenting at the 4th International Congress on 3D Materials Science (3DMS 2018).

The congress program includes, but is not limited to, the following technical topics:

- Methods for materials simulation, modeling, and characterization in 3D
- 3D data processing and reconstruction algorithms
- Process-microstructure-property relationships in 3D
- Materials dynamics in 3D

3DMS 2018 distills the most current knowledge of the field in a three-day learning and networking experience. Don't miss your opportunity to contribute. For more details and to submit your abstract, visit: **www.tms.org/3DMS2018**

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